

1.0A Avg.

30 Volts

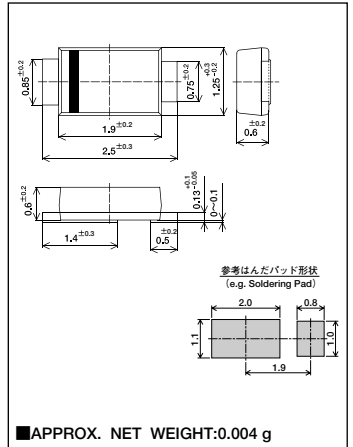
SBD

SA10LA03

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	30	V
直流順電流 Direct Forward Current	I_{DC}	直流通電 Direct Current $T_a=74^{\circ}C *1$	1.41 A
平均整流電流 Average rectified Forward Current	I_o	方形波通電 RECT 180°C Rectangular Wave 50% Duty $T_a=38^{\circ}C *1, V_{RM}=15V$ $T_l=91^{\circ}C, V_{RM}=15V$ (T_l : Lead Temperature)	1.0 A
サージ順電流 Surge Forward Current	I_{FSM}	20 (50Hz正弦半波1サイクル非くり返し) Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+125	°C
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	°C

■OUTLINE DRAWING(mm)



■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$V_{RM}=5V T_a=25^{\circ}C$ $V_{RM}=30V T_a=25^{\circ}C$	—	50	—	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$I_{FM}=0.7A T_a=25^{\circ}C$ $I_{FM}=1.0A T_a=25^{\circ}C$	—	0.5 0.33 0.39	1.5 0.37	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 (Junction to Ambient)	*1 (アルミナ基板実装)		100	°C/W
			*2 (ガラスエポキシ基板実装)		150	
	$R_{th(j-l)}$	接合部・リード間 (Junction to Lead)	—	—	30	

*1: プリント基板実装/Alumina Substrate Mounted (Soldering Land=6×6mm)
*2: プリント基板実装/Glass-Epoxy Substrate Mounted (Soldering Land=6×6mm)

■定格・特性曲線

FIG.1
順電圧特性
FORWARD CURRENT VS. VOLTAGE

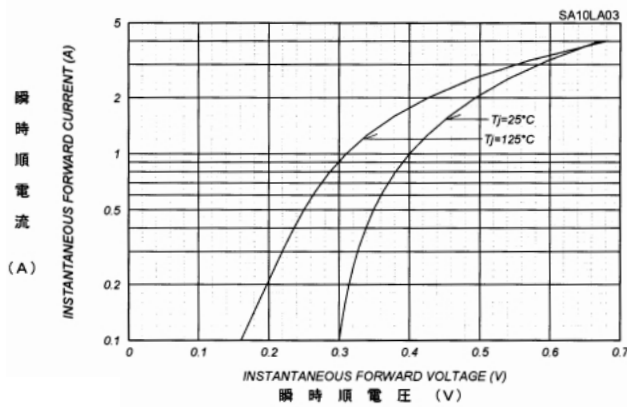


FIG.2
平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

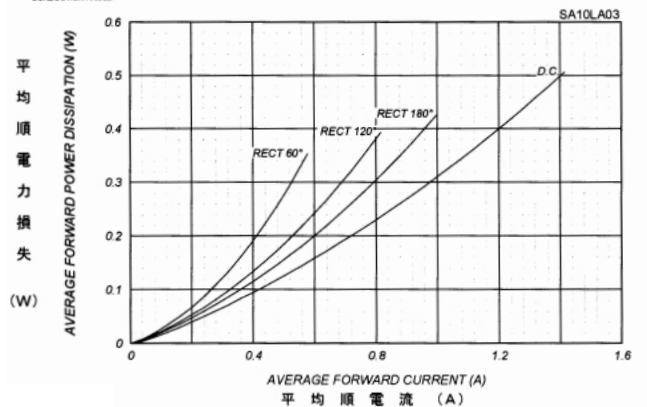


FIG.3
ピーク逆電流 - ピーク逆電圧特性
PEAK REVERSE CURRENT VS. PEAK REVERSE VOLTAGE
 $T_j=125^{\circ}C$

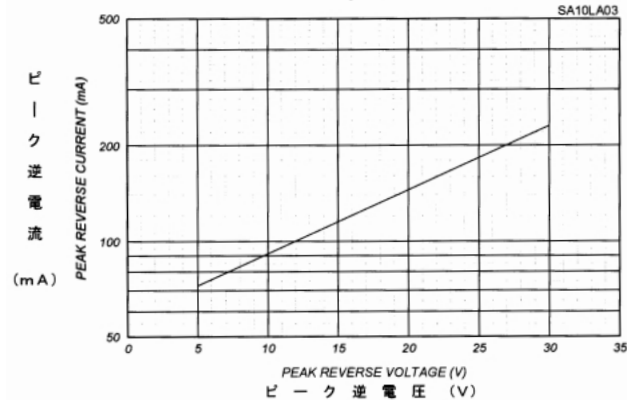
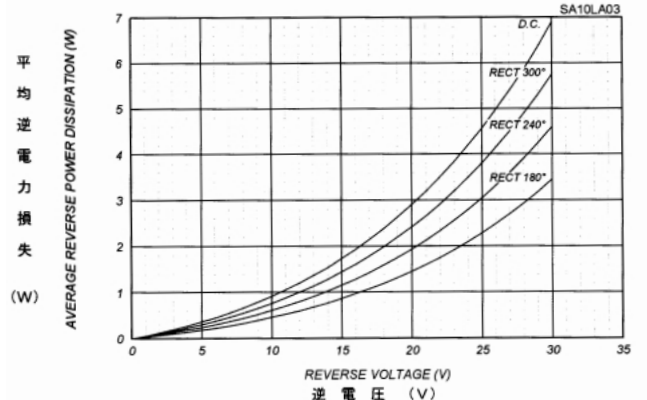


FIG.4
平均逆電力損失
AVERAGE REVERSE POWER DISSIPATION



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FIG.5

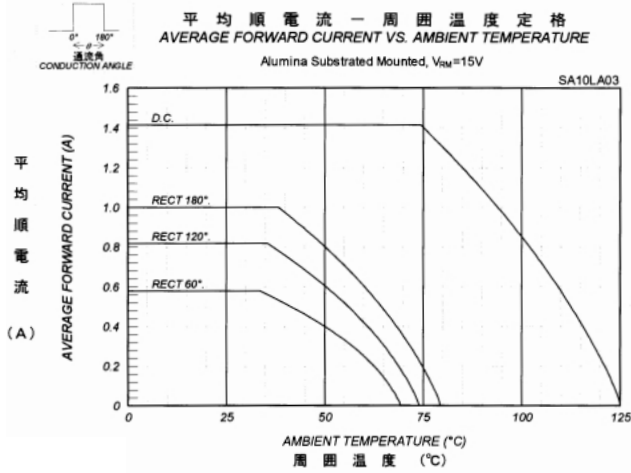


FIG.6

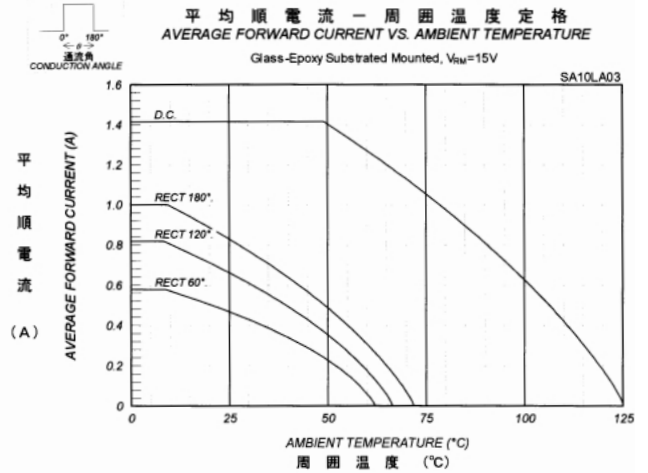


FIG.7

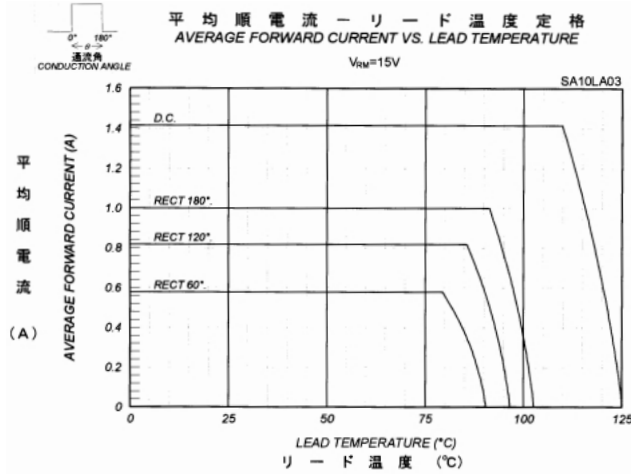


FIG.8

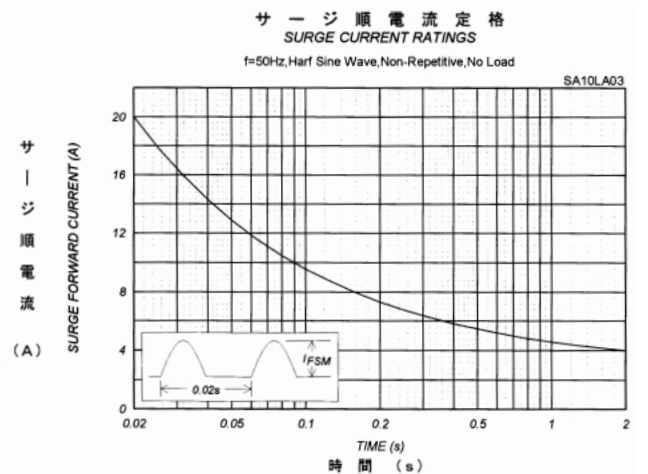


FIG.9

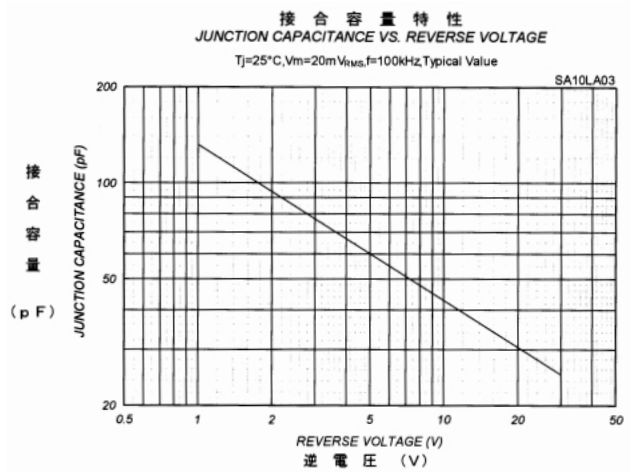


FIG.10

